
Non-Silicone thermally conductive putty

GCS-NSP30 is a non silicone putty

Features

- High compressibility
- Non-curing
- Pump out resistant
- Long term stability
- Electrical insulation
- Low/NO siloxanes, Siloxane Volatiles D4~D20 0%



Part number	Package
GCS-NSP30-100ml	100ml syringe

Applications

Displays, lighting protection

PDP TV, LCD CCFL and LCD LED display backlight, LED signage, projectors and new display technology.

Consumer and industrial electronics

Mobile telephone, communication base station, laptop, notebook, computer servers, handheld gaming devices, memory modules, CPU modules, amplifiers, batteries, and DC to DC convertors power supplies.

Automotive electronics

Engine management, electronic suspension, braking systems, communication and multimedia systems, comfort convenience features, vehicle lighting, vehicle controls, hybrid vehicle battery thermal management, electric vehicle thermal management.



Global Component Sourcing

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Characteristic	Test Method	Value
Colour	Visual	Light Grey
Thickness mm	-	0.5 - 2.0
Density g/cm ³	ASTM D792	3.0
Flow rate, (30cc EFD cartridge, 0.1", 90 psi) g/cm ³	-	5
Application temperature °C	-	-30 - +150
BLT Thickness low limit, mm	ASTM D374	0.08
Electrical		
Dielectric breakdown kV/mm	ASTM D419	>10
Dielectroc constant	ASTM D150	8
Volume resistivity Ohm-m	ASTM D257	>10 ¹³
Thermal		
Thermal conductivity W/m*K	ASTM D5470	3.0
Coefficient of Thermal Expansion, ppm/K	-	180

